

ABSTRACT OF THE DISCLOSURE

An electronic device of a chip size having improved airtightness is designed to be formed by a reduced number of process steps. An electronic component including a chip having a functional surface and electrodes at least on one side and a substrate having a portion which can be connected to the electrodes of the chip is designed as such an electronic device. In the electronic component, electroconductive glass or an intermetallic compound is used for connection portions to establish electrical connections between the chip and the substrate and to simultaneously seal the device surface on the chip.